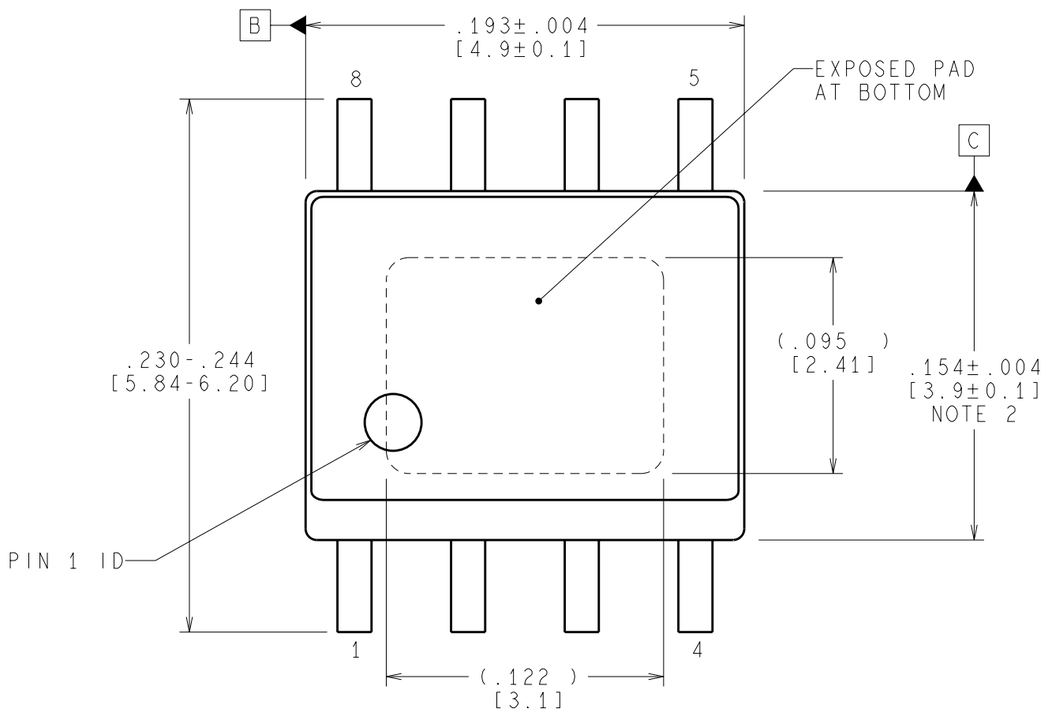
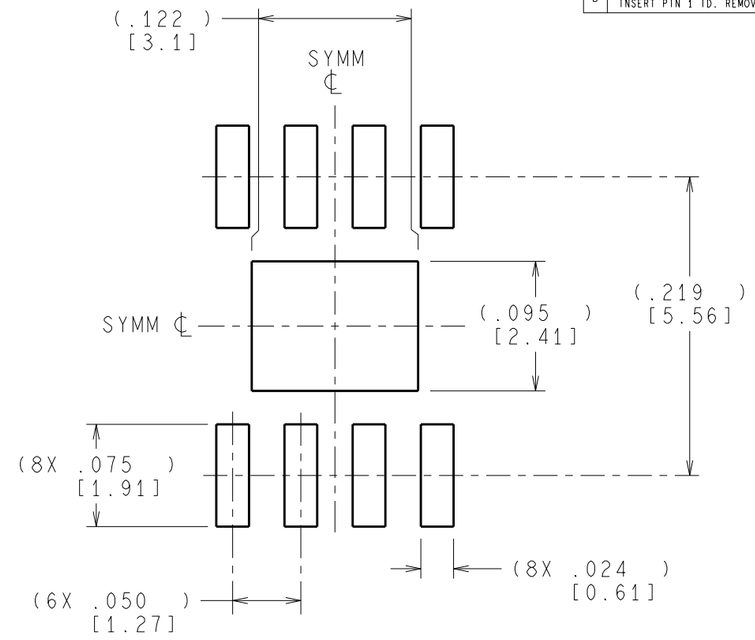
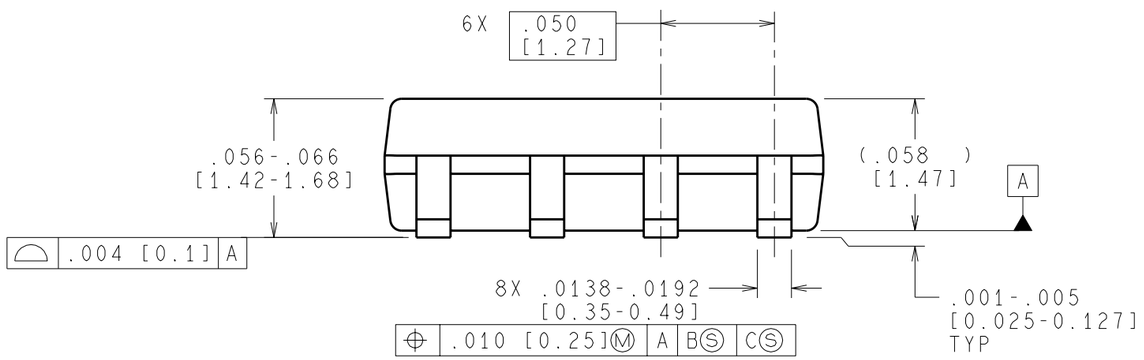
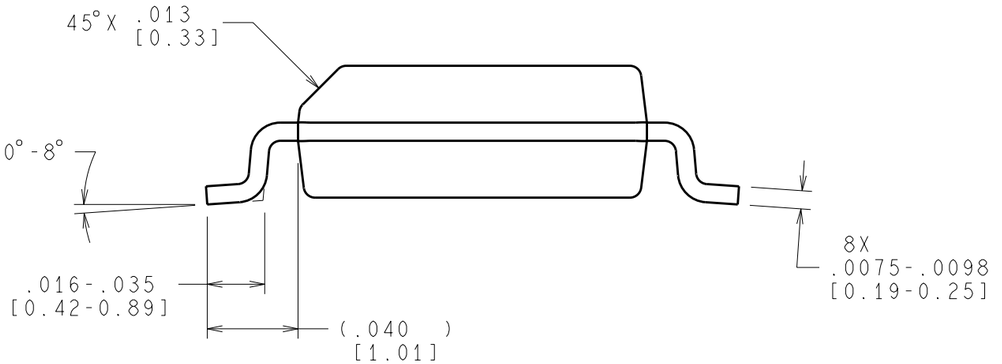
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1126	07/28/2003	TL/RW
B	CHANGE PKG BODY SIZE FROM .194x.155 TO .193x.154 INSERT PIN 1 ID. REMOVE -2 FROM DRAWING TITLE.	2429	12/11/2007	EL/TL/EL





RECOMMENDED LAND PATTERN





NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
2. DIMENSION DOES NOT INCLUDE MOLD FLASH.
3. REFERENCE JEDEC REGISTRATION MS-012, VARIATION AA.

CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS
DIMENSIONS IN ( ) FOR REFERENCE ONLY

APPROVALS	DATE
DRAWN THANH LEQUANG	07/28/2003
DFTG. CHK. THANH LEQUANG	12/11/2007
ENGR. CHK. EUGENE LEE	12/11/2007

PROJECTION INCH [MM]

National Semiconductor
2900 Semiconductor Dr. Santa Clara, CA 95052-8090

MOLDED, PSOP, .193x.154x.058 BODY, 8 LD, .050 PITCH, LARGE DAP

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-MRA08B	B

FORMERLY: N/A

SHEET 1 of 1